



# ELECTRODE ASSEMBLED BODY, CATHODE DEVICE AND PLATING DEVICE

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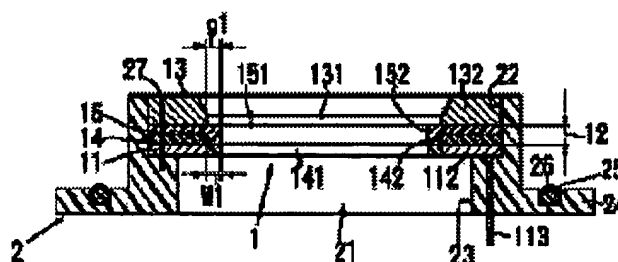
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## Abstract of JP11092993

**PROBLEM TO BE SOLVED:** To prevent the peeling of a plated film and to improve the repetitive reproducibility between wafers.

**SOLUTION:** A cathode member 11 has a hole surrounded by a frame part 112 and has a contact surface in contact with an object to be plated on one surface of the frame part 112. The cathode member 11 is constituted by using a conductive material such as a copper plate. The cathode member 11 is provided with a lead conductor 113. The insulating member 12 has holes 141, 151 surrounded by the frames parts. Frame parts 142, 152 are superimposed on the other surface (upper surface in a figure) of the frame part 112 of the cathode member 11. The inner periphery edge of the cathode member 11 is covered with the frame part 142 of a first insulating part 14 by a width of W1.



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